EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	2	automold$4	JPO	OR	ON	2006/06/14 09:24
L2	78	(mold$4 mould$4) and laser and resist	JPO	OR	ON	2006/06/14 09:27
L3	0	(mold$4 mould$4) and laser and resist and encapsulat$4	JPO	OR	ON	2006/06/14 09:25
L4	0	(mold$4 mould$4) and laser and resist and ablat$4	JPO	OR	ON	2006/06/14 09:27
L5	32	(mold$4 mould$4) and laser and resist and remov$4	JPO	OR	ON	2006/06/14 09:27
L6	25	(mold$4 mould$4) and laser and resist with remov$4	JPO	OR	ON	2006/06/14 09:27
L7	6	(mold$4 mould$4) and laser with resist with remov$4	JPO	OR	ON	2006/06/14 09:36
L8	2	(("5635671") or ("6221690")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:00
L9	139	(mold$4 mould$4) and laser with (nd yag nd:yag ndyag excimer)	JPO	OR	ON	2006/06/14 09:37
L10	13	(mold$4 mould$4) and laser with (nd yag nd:yag ndyag excimer) with remov$4	JPO	OR	ON	2006/06/14 09:40
L11	0	(mold$4 mould$4) and laser with (nd yag nd:yag ndyag excimer) with remov$4 and encapsulat$4	JPO	OR	ON	2006/06/14 09:40
L12	0	(mold$4 mould$4) and laser with (nd yag nd:yag ndyag excimer) and encapsulat$4	JPO	OR	ON	2006/06/14 09:40
L13	13	laser with (nd yag nd:yag ndyag excimer) and encapsulat$4	JPO	OR	ON	2006/06/14 09:49
L14	2	(laser with (clean$4 remov$4 ablat$4)) and ((encapsulat$4 mold$4 mould$4) with subsequent$4)	JPO	OR	ON	2006/06/14 09:52
L15	293	((clean$4 remov$4 ablat$4)) and (subsequent$4 adj7 (encapsulat$4 mold$4 mould$4))	JPO	OR	ON	2006/06/14 09:53
L16	0	(laser with (clean$4 remov$4 ablat$4)) and (subsequent$4 adj7 (encapsulat$4 mold$4 mould$4))	JPO	OR	ON	2006/06/14 10:10
L17	1980	(laser with (clean$4 remov$4 ablat$4)) and (after$5 near$7 (encapsulat$4 mold$4 mould$4))	JPO	OR	ON	2006/06/14 10:11
L18	47	(laser with (clean$4 remov$4 ablat$4)) and (after$5 with (encapsulat$4 mold$4 mould$4))	JPO	OR	ON	2006/06/14 10:17

L19	410	(laser with (clean$4 remov$4 ablat$4) with resin)	JPO	OR	ON	2006/06/14 10:17
L20	69	(laser with (clean$4 remov$4 ablat$4) with resin) and (mold$4 encapsulat$4)	JPO	OR	ON	2006/06/14 10:20
L21	2	(laser with (clean$4 remov$4 ablat$4) with resin) and (subsequent$4 with (mold$4 encapsulat$4))	JPO	OR	ON	2006/06/14 10:18
L22	77	(laser with (clean$4 remov$4 ablat$4) with (resist resin)) and (mold$4 encapsulat$4)	JPO	OR	ON	2006/06/14 10:21
L23	47	(laser with (clean$4 remov$4 ablat$4) with (resist resin)) and ((mold$4 encapsulat$4) with (clean$4 remov$4 ablat$4))	JPO	OR	ON	2006/06/14 10:36
L24	2	23 not 20	JPO	OR	ON	2006/06/14 10:37
L25	0	vision with system and (detect$4 with resist)	JPO	OR	ON	2006/06/14 10:37
L26	24	vision with system and (detect$4 with resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:38
L27	4	vision with system same (detect$4 with resist)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:40
L28	57	((visual$4 vision) with detect$4 with resist) not 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L29	0	((visual$4 vision) with detect$4 with resist) not 27 and ((mold$4 mould$4) with semiconduct$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L30	29	((visual$4 vision) with detect$4 with resist) not 27 and semiconduct$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:41
L32	8	((visual$4 vision) with detect$4 with resist) same semiconduct$4 not 27	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:52

L33	11	(("4987286") or ("5023424") or ("5495126") or ("5634230") or ("5950071") or ("6566169") or ("4904498") or ("5852870") or ("5928533") or ("6281090") or ("6866910")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 10:52
L34	4	"20040209376" "20020089058"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:53
L35	15	33 34	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:53
L36	2	35 and laser with (resist resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 10:54
L37	1	("5364493").PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:01
L38	3	8 37	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:02
L39	3	38 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:02
L40	2	38 and laser with remov$4 with (resist resin)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:14
L41	0	38 and laser with remov$4 with (resist resin) same (mold$4 mould$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:03
L42	688	semiconductor with (mold$4 automold$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:15

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L43	203	semiconductor with (mold$4 automold$4) with laser with (encapsulat$4 seal$4 packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:15
L44	33	semiconductor with (mold$4 automold$4) with laser with (encapsulat$4 seal$4 packag$4) with (remov$4 etch$4 ablat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:16
L45	1	semiconductor with (automold$4) with laser with (encapsulat$4 seal$4 packag$4) with (remov$4 etch$4 ablat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:18
L46	1	semiconductor with (automold$4) with laser with (encapsulat$4 seal$4 packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L47	2	semiconductor with (automold$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L48	2	(automold$4) with laser with (encapsulat$4 seal$4 packag$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L49	9	(automold$4) with laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:17
L50	259	semiconductor with laser with (encapsulat$4 seal$4 packag$4) with (remov$4 etch$4 ablat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:18
L51	41	semiconductor with laser with (encapsulat$4 seal$4 packag$4) with (remov$4 etch$4 ablat$4) with (mold$4 mould$4 injection)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:19
L52	33	automold$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:24

L53	9	automold$4 with semiconduct$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:21
L54	1	("5352107").PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:21
L55	0	54 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:21
L56	0	54 and (uv ultraviolet infrared ir heat$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:22
L57	18	52 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:28
L58	6	52 and laser and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:28
L59	0	52 and laser and (visual$4 camera)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:29
L60	0	52 and laser and video$9	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:29
L61	14	52 and laser and view$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:39
L62	3	(("5352107") or ("6465743") or ("3767304")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 11:39
L63	0	62 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/06/14 11:39

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S1	16	(("5607601") or ("6587009") or ("3866398") or ("4752668") or ("4894115") or ("5104480") or ("5147680") or ("5442416") or ("6242079") or ("6245677") or ("6376290") or ("6537743") or ("6550989") or ("5950071") or ("4746390") or ("6670222")).PN.	USPAT; USOCR	OR	OFF	2006/06/14 09:23
S2	2	"20030003688"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:50
S3	18	S1 S2	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:51
S4	1207	resist with laser with remov$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:52
S5	31	S4 and (bga "ball grid" "ball-grid")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 12:53
S6	16	S5 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:14
S7	10	S3 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 13:14
S8	3	S4 and S7	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:21
S9	7	S7 not S8	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:09

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S10	0	(photoresist photolithograph$4) with (wafer semiconduct$4) with automold$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:10
S11	5	(photoresist photolithograph$4) same (wafer semiconduct$4) same automold$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S12	31	automold$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S13	23	S12 and (silicon semiconduct$5 wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:11
S14	16	S12 and laser	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:25
S15	6	S14 and (nd yag ndyag excimer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:27
S16	10	S14 not S15	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:39
S17	4	S16 and degat$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:47
S18	0	S16 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:48
S19	5	S12 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:48

S20	10	S4 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:51
S21	1	("6025256").PN.	USPAT; USOCR	OR	OFF	2005/09/13 14:52
S22	0	S21 and vision	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/13 14:52